



Material Content Data Sheet



Sales Product Name		ICE2QR0665G		Issued		19. July 2018		
MA#		MA001582598						
Package		PG-DSO-12-19		Weight*		154.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.048	1.32	1.32	13215	13215
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.069	0.04		447	
	non noble metal	iron	7439-89-6	1.386	0.89		8944	
wire	non noble metal	copper	7440-50-8	56.286	36.32	37.26	363175	372678
	noble metal	gold	7440-57-5	0.241	0.16	0.16	1554	1554
	encapsulation	organic material	carbon black	1333-86-4	0.277	0.18		1789
encapsulation	plastics	epoxy resin	-	10.815	6.98		69780	
	inorganic material	silicondioxide	60676-86-0	81.341	52.48	59.64	524838	596407
leadfinish	non noble metal	tin	7440-31-5	1.143	0.74	0.74	7373	7373
plating	noble metal	silver	7440-22-4	0.428	0.28	0.28	2765	2765
glue	plastics	epoxy resin	-	0.140	0.09		901	
	noble metal	silver	7440-22-4	0.792	0.51	0.60	5107	6008
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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